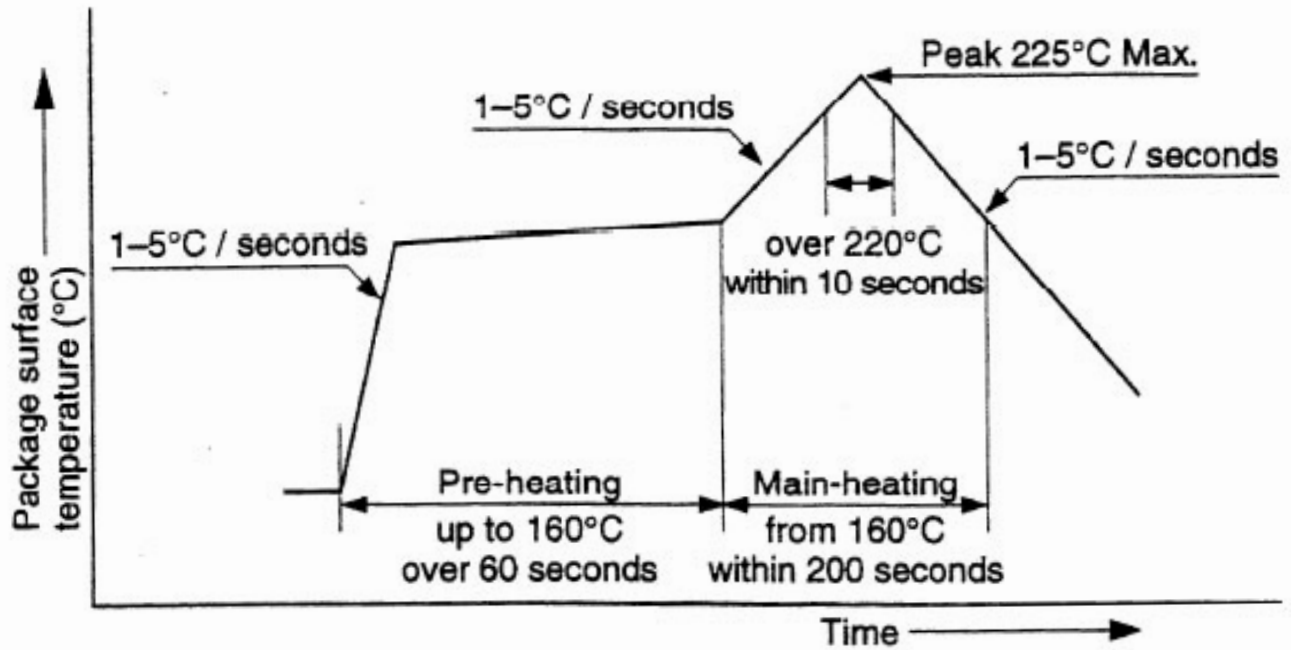


Temperature Profile for PBGA Packages

This process combines air reflow and infrared reflow. The resin surface temperature at maximum should be 235°C for not longer than 10 seconds. It is preferred that the time and temperature are shorter.



PLX Technology, Inc.
 870 Maude Ave.
 Sunnyvale, CA 94085 USA

Tel: 408 774 9060
 Fax: 408 774 2169
 Email: info@plxtech.com